

# BLM9D2527-20AB

LDMOS 2-stage integrated Doherty MMIC

Rev. 1 — 29 June 2017

AMPLEON

Product data sheet

## 1. Product profile

### 1.1 General description

The BLM9D2527-20AB is a 2-stage fully integrated Doherty MMIC solution using Ampleon's state of the art GEN9 LDMOS technology. The carrier and peaking device, input splitter and output combiner are integrated in a single package. This multiband device is perfectly suited as a final device in massive MIMO or small cell applications in the frequency range from 2500 MHz to 2700 MHz. Available in PQFN outline.

**Table 1. Performance**

Typical RF performance at  $T_{case} = 25\text{ °C}$ ;  $I_{DQ} = 43\text{ mA}$  (driver and final stages);

$V_{GSq(peaking)} = V_{GSq(carrier)} - 0.75\text{ V}$ . Test signal: 3GPP test model 1; 64 DPCH; PAR = 9.9 dB at 0.01 % probability on CCDF.

| Test signal           | f     | V <sub>DS</sub> | P <sub>L(AV)</sub> | G <sub>p</sub> | η <sub>D</sub> | ACPR <sub>5M</sub> |
|-----------------------|-------|-----------------|--------------------|----------------|----------------|--------------------|
|                       | (MHz) | (V)             | (W)                | (dB)           | (%)            | (dBc)              |
| single carrier W-CDMA | 2620  | 28              | 3.8                | 27.3           | 46.1           | -33.3              |

### 1.2 Features and benefits

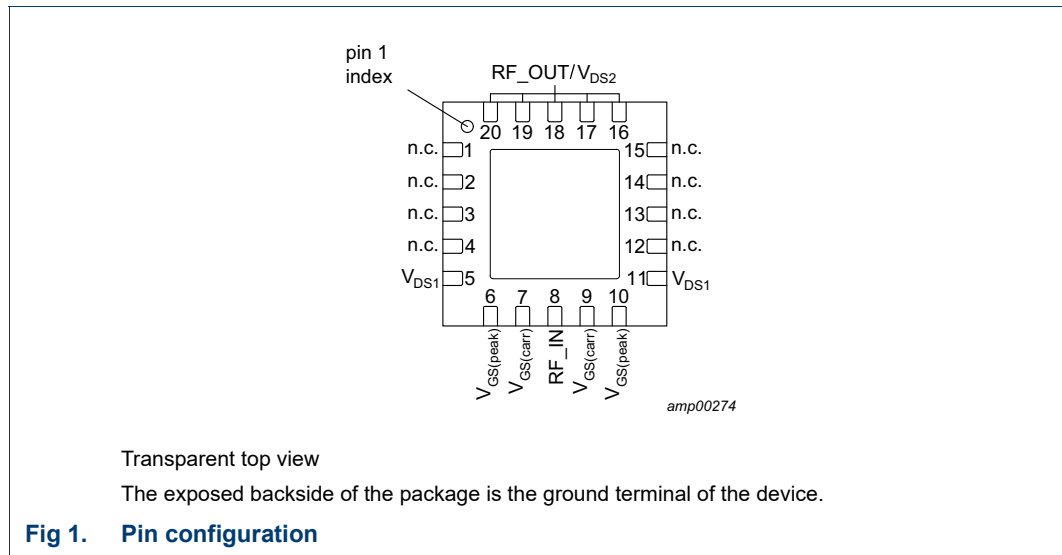
- Integrated input splitter
- Integrated output combiner
- Very high efficiency thanks to asymmetry
- Designed for broadband operation (frequency 2500 MHz to 2700 MHz)
- Independent control of carrier and peaking bias
- Integrated ESD protection
- Excellent thermal stability
- Source impedance 50 Ω; high power gain
- Compliant to Directive 2002/95/EC, regarding restriction of hazardous substances (RoHS)

### 1.3 Applications

- RF power MMIC for multi-carrier and multi-standard GSM, W-CDMA and LTE base stations in the 2500 MHz to 2700 MHz frequency range.

## 2. Pinning information

### 2.1 Pinning



### 2.2 Pin description

Table 2. Pin description

| Symbol            | Pin | Description                                      |
|-------------------|-----|--|
| n.c.              | 1   | not connected                                    |
| n.c.              | 2   | not connected                                    |
| n.c.              | 3   | not connected                                    |
| n.c.              | 4   | not connected                                    |
| $V_{DS1}$         | 5   | drain-source voltage of driver stages            |
| $V_{GS(peak)}$    | 6   | gate-source voltage of peaking                   |
| $V_{GS(carr)}$    | 7   | gate-source voltage of carrier                   |
| RF_IN             | 8   | RF input   |
| $V_{GS(carr)}$    | 9   | gate-source voltage of carrier                   |
| $V_{GS(peak)}$    | 10  | gate-source voltage of peaking                   |
| $V_{DS1}$         | 11  | drain-source voltage of driver stages            |
| n.c.              | 12  | not connected                                    |
| n.c.              | 13  | not connected                                    |
| n.c.              | 14  | not connected                                    |
| n.c.              | 15  | not connected                                    |
| RF_OUT/ $V_{DS2}$ | 16  | RF output / drain-source voltage of final stages |
| RF_OUT/ $V_{DS2}$ | 17  | RF output / drain-source voltage of final stages |
| RF_OUT/ $V_{DS2}$ | 18  | RF output / drain-source voltage of final stages |

Table 2. Pin description ...continued

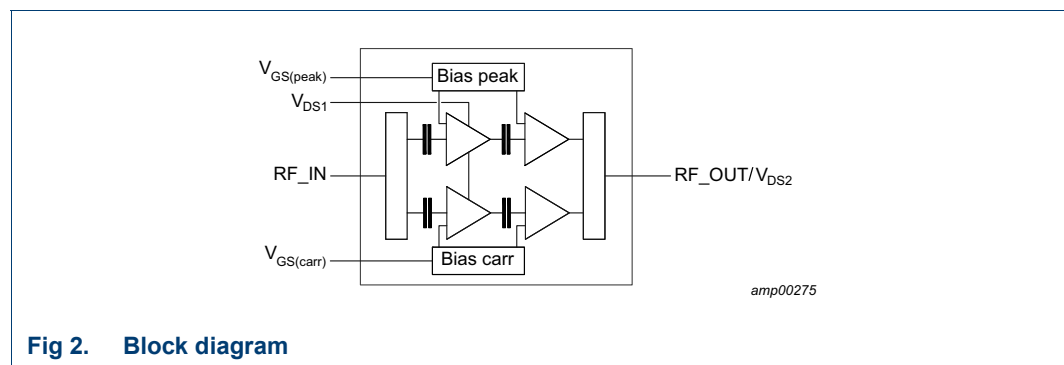
| Symbol            | Pin    | Description                                      |
|-------------------|--------|--|
| RF_OUT/ $V_{DS2}$ | 19     | RF output / drain-source voltage of final stages |
| RF_OUT/ $V_{DS2}$ | 20     | RF output / drain-source voltage of final stages |
| GND               | flange | RF ground  |

### 3. Ordering information

Table 3. Ordering information

| Type number    | Package |   |           |
|----------------|---------|---|-----------|
|                | Name    | Description   | Version   |
| BLM9D2527-20AB | PQFN20  | plastic thermal enhanced quad flat package; no leads; 20 terminals; body 8.0 x 8.0 x 2.1 mm | SOT1462-1 |

### 4. Block diagram



### 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter            | Conditions | Min  | Max  | Unit |
|-----------|----------------------|------------|------|------|------|
| $V_{DS}$  | drain-source voltage |            | -    | 65   | V    |
| $V_{GS}$  | gate-source voltage  |            | -0.5 | +13  | V    |
| $T_{stg}$ | storage temperature  |            | -65  | +150 | °C   |
| $T_j$     | junction temperature | [1]        | -    | 175  | °C   |

[1] Continuous use at maximum temperature will affect the reliability. For details refer to the online MTF calculator.

## 6. Thermal characteristics

**Table 5. Thermal characteristics**

Measured for total device.

| Symbol        | Parameter                                | Conditions   | Value | Unit |
|---------------|--|--|-------|------|
| $R_{th(j-c)}$ | thermal resistance from junction to case | $T_{case} = 90\text{ °C}; P_{L(AV)} = 3\text{ W}$ [1]    | 12    | K/W  |
|               |  | $T_{case} = 90\text{ °C}; P_{L(AV)} = 1.25\text{ W}$ [1] | 17    | K/W  |

[1] When operated with a 1-carrier W-CDMA with PAR = 8 dB.

## 7. Characteristics

**Table 6. DC characteristics**

$T_{case} = 25\text{ °C}$ ; unless otherwise specified.

| Symbol               | Parameter                     | Conditions                                  | Min  | Typ | Max  | Unit          |
|----------------------|-------------------------------|---|------|-----|------|---------------|
| <b>Carrier</b>       |                               |   |      |     |      |               |
| $V_{GSq}$            | gate-source quiescent voltage | $V_{DS} = 28\text{ V}; I_D = 37\text{ mA}$  | 1.65 | 2.2 | 2.75 | V             |
| $I_{GSS}$            | gate leakage current          | $V_{GS} = 1\text{ V}; V_{DS} = 0\text{ V}$  | -    | -   | 140  | nA            |
| <b>Peaking</b>       |                               |   |      |     |      |               |
| $I_{GSS}$            | gate leakage current          | $V_{GS} = 1\text{ V}; V_{DS} = 0\text{ V}$  | -    | -   | 140  | nA            |
| <b>Final stages</b>  |                               |   |      |     |      |               |
| $I_{DSS}$            | drain leakage current         | $V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$ | -    | -   | 1.4  | $\mu\text{A}$ |
| <b>Driver stages</b> |                               |   |      |     |      |               |
| $I_{DSS}$            | drain leakage current         | $V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$ | -    | -   | 1.4  | $\mu\text{A}$ |

**Table 7. RF Characteristics**

Typical RF performance at  $T_{case} = 25\text{ °C}$ ;  $V_{DS} = 28\text{ V}$ ;  $I_{Dq} = 37\text{ mA}$  (carrier);

$V_{GSq(peaking)} = V_{GSq(carrier)} - 0.5\text{ V}$ ;  $P_L = 2\text{ W}$ ;  $f = 2.7\text{ GHz}$ . Unless otherwise specified, measured in an Ampleon production circuit.

| Symbol                 | Parameter                             | Conditions         | Min | Typ  | Max | Unit |
|------------------------|---------------------------------------|--------------------|-----|------|-----|------|
| <b>Test signal: CW</b> |                                       |                    |     |      |     |      |
| $G_p$                  | power gain                            |                    | 26  | 27.2 | 29  | dB   |
| $\eta_D$               | drain efficiency                      | $P_L = 2\text{ W}$ | 36  | 41   | -   | %    |
|                        |                                       | $P_L = P_{L(3dB)}$ | 50  | 56   | -   | %    |
| $RL_{in}$              | input return loss                     |                    | -   | -19  | -10 | dB   |
| $P_{L(3dB)}$           | output power at 3 dB gain compression |                    | 43  | 43.6 | -   | dBm  |

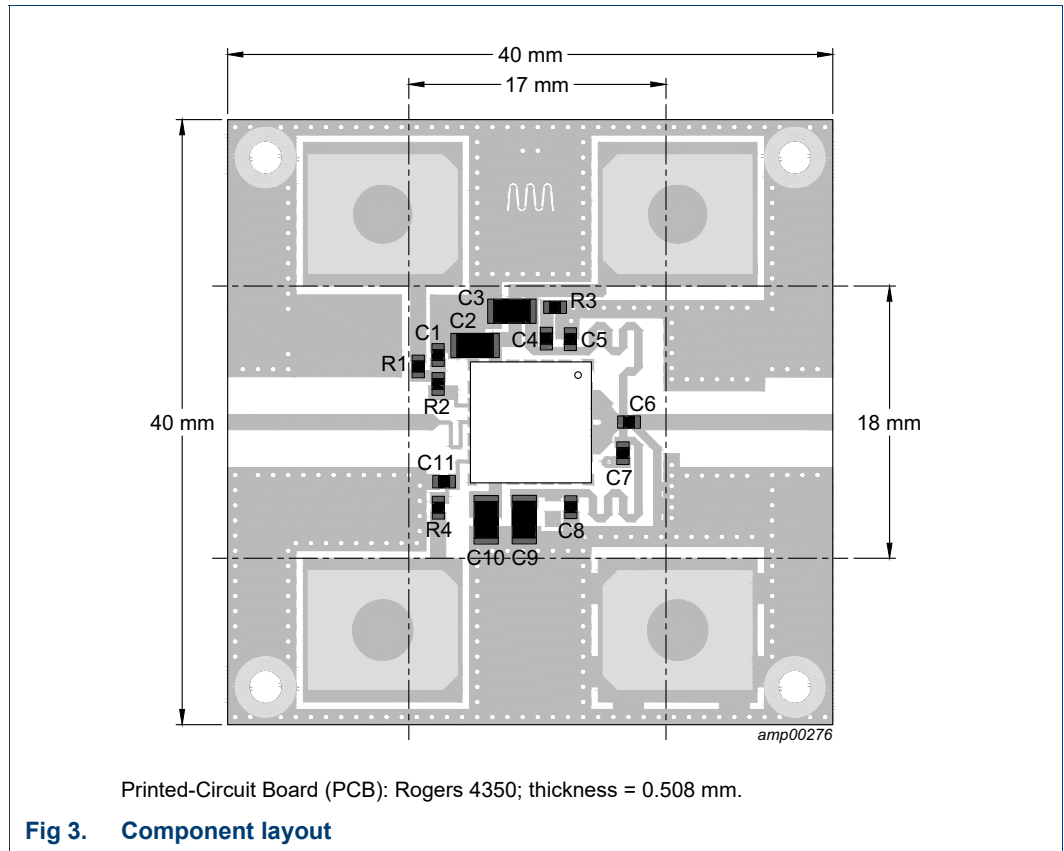
## 8. Application information

**Table 8. Typical performance**

Test signal: 1-carrier W-CDMA;  $T_{case} = 25\text{ °C}$ ;  $V_{DS} = 28\text{ V}$ ;  $I_{DQ} = 43\text{ mA}$  (driver and final stages); test model 1; 64 DPCH; PAR = 9.9 dB at 0.01 % probability CCDF; unless otherwise specified, measured in an Ampleon 2620 MHz to 2690 MHz frequency band asymmetrical Doherty application circuit.

| Symbol                              | Parameter                             | Conditions  | Min | Typ   | Max | Unit  |
|-------------------------------------|---------------------------------------|---|-----|-------|-----|-------|
| $P_{L(3dB)}$                        | output power at 3 dB gain compression | f = 2655 MHz <a href="#">[1]</a>  | -   | 43.4  | -   | dBm   |
| $\varphi_{s21}/\varphi_{s21(norm)}$ | normalized phase response             | f = 2655 MHz; at 3 dB compression point <a href="#">[2]</a>                         | -   | -14.5 | -   | °     |
| $\eta_D$                            | drain efficiency                      | 8 dB OBO ( $P_{L(AV)} = 35.8\text{ dBm}$ ); f = 2620 MHz                            | -   | 46.1  | -   | %     |
| $G_p$                               | power gain                            | $P_{L(AV)} = 35.8\text{ dBm}$ ; f = 2620 MHz  | -   | 27.3  | -   | dB    |
| $B_{video}$                         | video bandwidth                       | $P_{L(AV)} = 34.5\text{ dBm}$ set to obtain IMD3 = -30 dBc; 2-tone CW; f = 2655 MHz | -   | 265   | -   | MHz   |
| $G_{flat}$                          | gain flatness                         | $P_{L(AV)} = 35.8\text{ dBm}$ ; f = 2620 MHz to 2170 MHz                            | -   | 0.2   | -   | dB    |
| $ACPR_{5M}$                         | adjacent channel power ratio (5M)     | $P_{L(AV)} = 35.8\text{ dBm}$ ; f = 2655 MHz  | -   | -33.3 | -   | dBc   |
| $\Delta G/\Delta T$                 | gain variation with temperature       | f = 2655 MHz  | -   | 0.04  | -   | dB/°C |
| K                                   | Rollett stability factor              | $T_{case} = -40\text{ °C}$ ; f = 0.15 GHz to 5 GHz <a href="#">[3]</a>              | -   | >1.7  | -   |       |

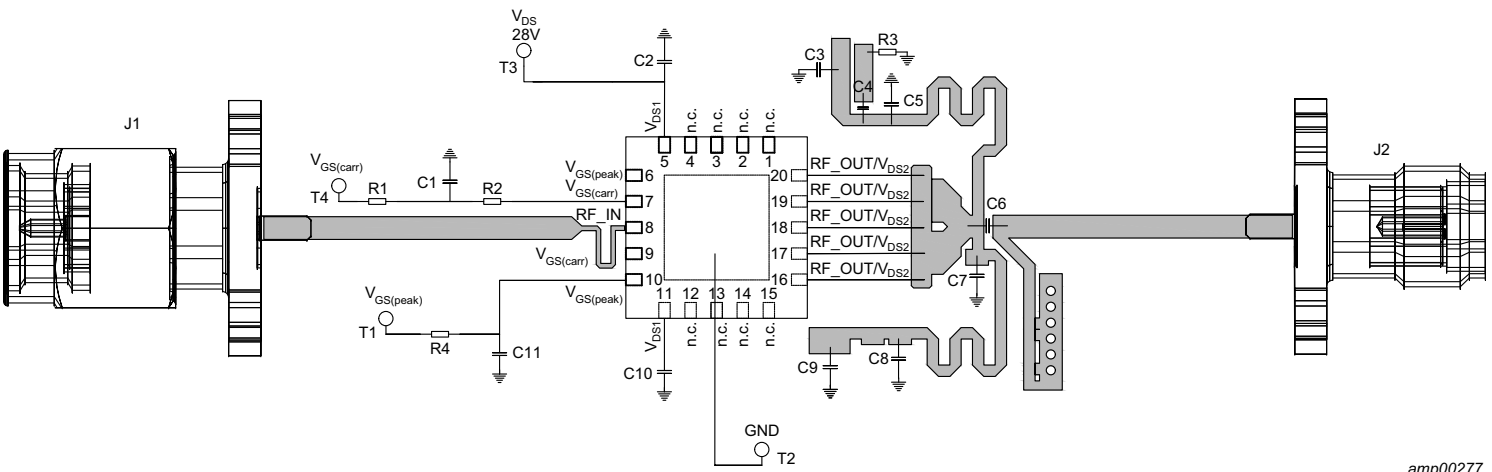
- [1] Pulsed CW power sweep measurement ( $\delta = 10\%$ ,  $t_p = 100\text{ }\mu\text{s}$ ).
- [2] 25 ms CW power sweep measurement.
- [3] S-parameters measured with load-pull jig.



**Table 9. Demo test circuit list of components**

See [Figure 3](#) for component layout.

| Component       | Description                        | Value                               | Remarks                              |
|-----------------|------------------------------------|-------------------------------------|--------------------------------------|
| C1, C11         | multilayer ceramic chip capacitor  | 10 $\mu$ F, 50 V                    | Murata: GRM31CR61H106KA12L           |
| C2, C3, C9, C10 | multilayer ceramic chip capacitor  | 1 $\mu$ F, 6.3 V                    | TDK: C1608X5R0J106K080AB             |
| C4              | multilayer ceramic chip capacitor  | 100 pF                              | Murata: GQM1875C2E1R6BB12            |
| C5, C8          | multilayer ceramic chip capacitor  | 4.7 pF                              | Murata: GQM1875C2E5R6BB12            |
| C6              | multilayer ceramic chip capacitor  | 1.8 pF                              | Murata: GQM1875C2E7R5BB12            |
| C7              | multilayer ceramic chip capacitor  | 1.6 pF                              | Murata: GQM1875C2ER50BB12            |
| J1              | SMA Coaxial panel connector male   |                                     | Hubner & Suhner: 13_SMA-50-0-2/111_N |
| J2              | SMA Coaxial panel connector female |                                     | Hubner & Suhner: 13_SMA-50-0-2/111_N |
| R1              | SMD resistor                       | 820 $\Omega$ , $\pm 1$ %            | Multicomp: MC805                     |
| R2              | SMD resistor                       | 5.1 $\Omega$ , $\pm 1$ %            | Multicomp: MC805                     |
| R3, R4          | SMD resistor                       | 10 $\Omega$ , $\pm 1$ %             | Multicomp: MC805                     |
| T1, T2, T3, T4  | PCB Terminal                       | 6.35 mm $\times$ 0.81 mm;<br>4.1 mm | TE connectivity                      |



amp00277

Fig 4. Electrical schematic

### 8.1 Ruggedness in a Doherty operation

The BLM9D2527-20AB is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS} = 32\text{ V}$ ;  $I_{Dq} = 37\text{ mA}$  (carrier);  $V_{GSq(peak)} = V_{GSq(carrier)} - 0.5\text{ V}$ ;  $P_1$  corresponding to  $P_{L(3dB)}$  under  $Z_S = 50\ \Omega$  load;  $f = 2700\text{ MHz}$  (CW);  $T_{case} = 25\text{ }^\circ\text{C}$ .

### 8.2 Impedance information

**Table 10. Typical impedance for optimum Doherty operation**

Measured load-pull data per section; test signal: pulsed CW;  $T_{case} = 25\text{ }^\circ\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  $I_{Dq} = 35\text{ mA}$  (carrier);  $V_{GSq(peak)} = V_{GSq(carrier)} - 0.5\text{ V}$ ;  $t_p = 100\ \mu\text{s}$ ;  $\delta = 10\%$ . Typical values.

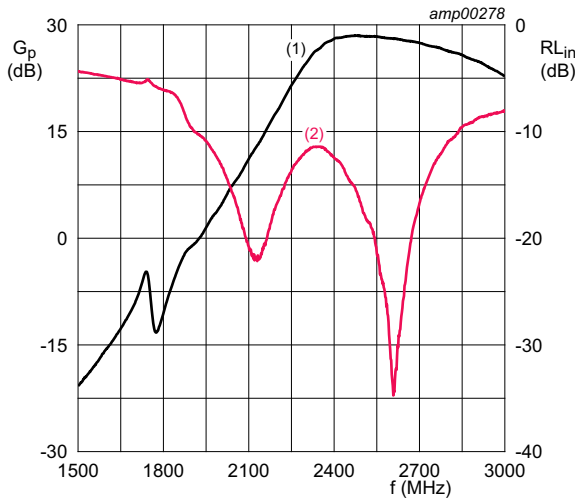
| f<br>(MHz) | tuned for optimum Doherty operation |                      |                |                         |                         |
|------------|-------------------------------------|----------------------|----------------|-------------------------|-------------------------|
|            | $Z_L$<br>( $\Omega$ )               | $G_{p(max)}$<br>(dB) | $P_L$<br>(dBm) | $\eta_{add}$ [1]<br>(%) | $\eta_{add}$ [2]<br>(%) |
| 2450       | 4.97 – j0.76                        | 28.60                | 43.80          | 51.00                   | 51.30                   |
| 2500       | 5.48 – j0.92                        | 28.60                | 43.80          | 51.20                   | 52.80                   |
| 2500       | 5.97 – j1.02                        | 28.40                | 43.90          | 53.30                   | 52.20                   |
| 2600       | 6.73 – j1.22                        | 28.30                | 43.70          | 53.80                   | 52.00                   |
| 2650       | 7.20 – j1.31                        | 28.20                | 43.70          | 54.70                   | 52.10                   |
| 2700       | 7.59 – j1.21                        | 28.20                | 43.60          | 56.50                   | 52.40                   |
| 2750       | 7.93 – j1.04                        | 28.00                | 43.50          | 56.60                   | 50.30                   |

[1] at 43 dBm (nearly 3 dB compression point).

[2] at 35 dBm (nearly 8 dB OBO point).

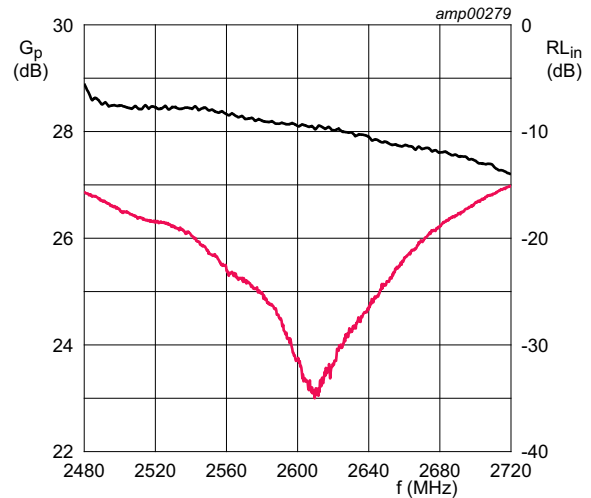


8.3 Graphs



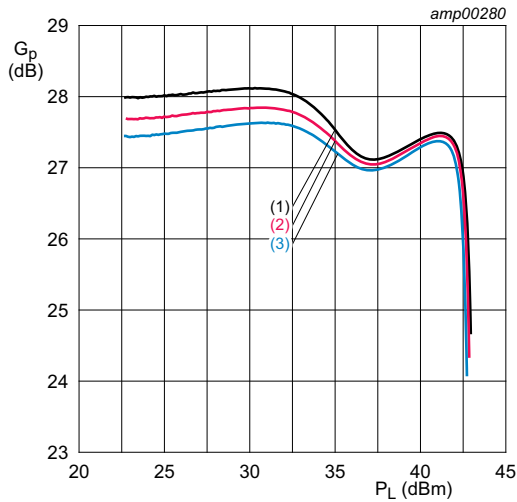
$T_{case} = 25\text{ }^\circ\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  $P_L = 1\text{ W}$ ;  
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).  
 Test signal: CW.  
 (1) magnitude of  $G_p$   
 (2) magnitude of  $RL_{in}$

Fig 5. Wideband power gain and input return loss as function of frequency; typical values



$T_{case} = 25\text{ }^\circ\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  $P_L = 1\text{ W}$ ;  
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).  
 Test signal: CW.  
 (1) magnitude of  $G_p$   
 (2) magnitude of  $RL_{in}$

Fig 6. In-band power gain and input return loss as function of frequency; typical values

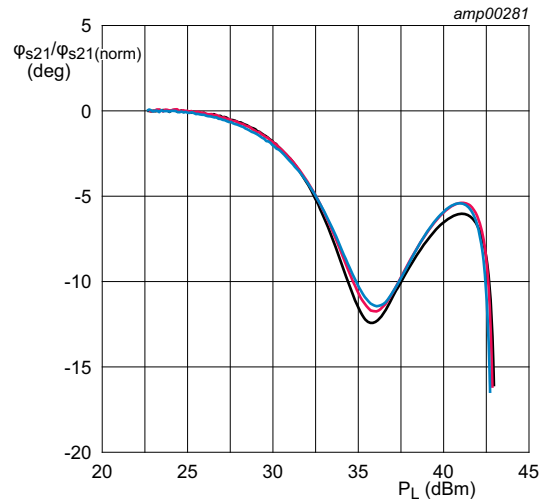


$T_{case} = 25\text{ }^{\circ}\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).

Test signal: CW.

- (1)  $f = 2620\text{ MHz}$
- (2)  $f = 2655\text{ MHz}$
- (3)  $f = 2690\text{ MHz}$

**Fig 7. Power gain as a function of output power; typical values**

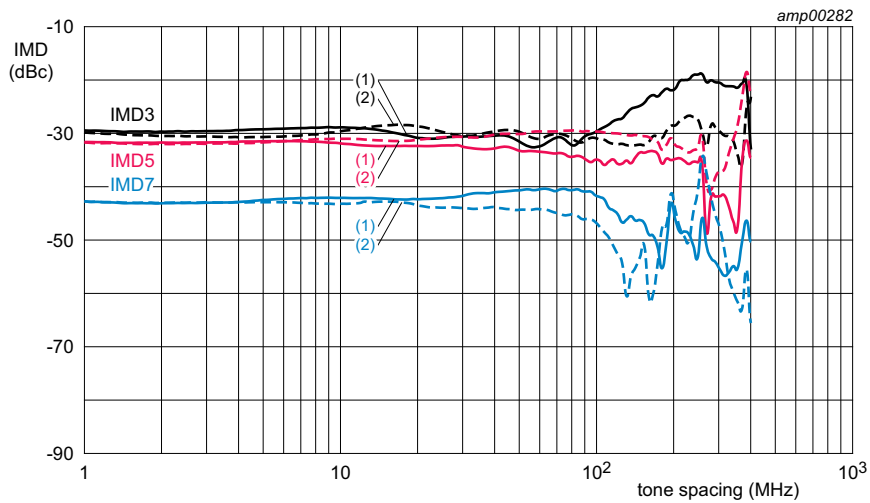


$T_{case} = 25\text{ }^{\circ}\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).

Test signal: CW.

- (1)  $f = 2620\text{ MHz}$
- (2)  $f = 2655\text{ MHz}$
- (3)  $f = 2690\text{ MHz}$

**Fig 8. Normalized phase response as a function of output power; typical values**

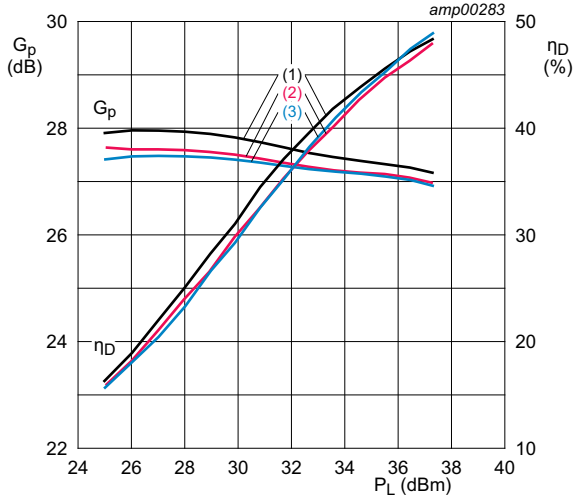


$T_{case} = 25\text{ }^{\circ}\text{C}$ ;  $V_{DS} = 28\text{ V}$ ;  $P_L = 34.5\text{ dBm}$ ;  $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  $V_{GS} = 1.54\text{ V}$  (peaking stage).

Test signal: CW.

- (1) IMD low
- (2) IMD high

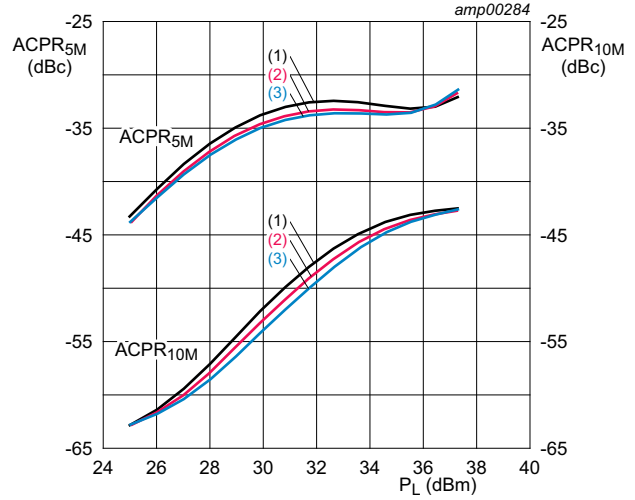
**Fig 9. Intermodulation distortion as a function of tone spacing; typical values**



$T_{case} = 25\text{ }^{\circ}\text{C}; V_{DS} = 28\text{ V};$   
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).  
 Test signal: 1-carrier W-CDMA; test model 1; 64 DPCH;  
 PAR = 9.9 dB at 0.01 % probability CCDF.

- (1)  $f = 2620\text{ MHz}$
- (2)  $f = 2655\text{ MHz}$
- (3)  $f = 2690\text{ MHz}$

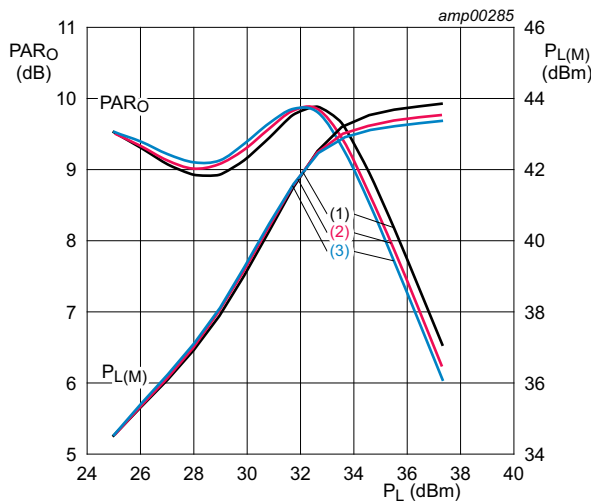
**Fig 10. Power gain and drain efficiency as function of output power; typical values**



$T_{case} = 25\text{ }^{\circ}\text{C}; V_{DS} = 28\text{ V};$   
 $I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  
 $V_{GS} = 1.54\text{ V}$  (peaking stage).  
 Test signal: 1-carrier W-CDMA; test model 1; 64 DPCH;  
 PAR = 9.9 dB at 0.01 % probability CCDF.

- (1)  $f = 2620\text{ MHz}$
- (2)  $f = 2655\text{ MHz}$
- (3)  $f = 2690\text{ MHz}$

**Fig 11. Adjacent channel power ratio as a function of output power; typical values**



$T_{case} = 25\text{ }^{\circ}\text{C}; V_{DS} = 28\text{ V}; I_{Dq1} + I_{Dq2} = 43\text{ mA}$  (carrier and peaking stages);  
 $V_{GS} = 2.29\text{ V}$  (carrier stage);  $V_{GS} = 1.54\text{ V}$  (peaking stage).  
 Test signal: 1-carrier W-CDMA; test model 1; 64 DPCH; PAR = 9.9 dB at 0.01 % probability CCDF.

- (1)  $f = 2620\text{ MHz}$
- (2)  $f = 2655\text{ MHz}$
- (3)  $f = 2690\text{ MHz}$

**Fig 12. Output peak-to-average ratio and peak output power as function of output power; typical values**



## 10. Handling information

**CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

**Table 11. ESD sensitivity**

| ESD model  | Class                   |
|--|-------------------------|
| Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002 | C2B <a href="#">[1]</a> |
| Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001     | 1B <a href="#">[2]</a>  |

[1] CDM classification C2B is granted to any part that passes after exposure to an ESD pulse of 750 V, but fails after exposure to an ESD pulse of 1000 V.

[2] HBM classification 1B is granted to any part that passes after exposure to an ESD pulse of 500 V, but fails after exposure to an ESD pulse of 1000 V.

## 11. Abbreviations

**Table 12. Abbreviations**

| Acronym | Description                                    |
|---------|--|
| AM      | Amplitude Modulation                           |
| 3GPP    | 3rd Generation Partnership Project             |
| CCDF    | Complementary Cumulative Distribution Function |
| CW      | Continuous Wave                                |
| DPCH    | Dedicated Physical CHannel                     |
| ESD     | ElectroStatic Discharge                        |
| GEN9    | Ninth Generation                               |
| GSM     | Global System for Mobile Communications        |
| LDMOS   | Laterally Diffused Metal Oxide Semiconductor   |
| LTE     | Long Term Evolution                            |
| MIMO    | Multiple Input Multiple Output                 |
| MMIC    | Monolithic Microwave Integrated Circuit        |
| MTF     | Median Time to Failure                         |
| OBO     | Output Back Off                                |
| PAR     | Peak-to-Average Ratio                          |
| PM      | Phase Modulation                               |
| SMD     | Surface Mounted Device                         |
| VSWR    | Voltage Standing-Wave Ratio                    |
| W-CDMA  | Wideband Code Division Multiple Access         |

## 12. Revision history

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Table 13. Revision history

| Document ID        | Release date | Data sheet status  | Change notice | Supersedes |
|--------------------|--------------|--------------------|---------------|------------|
| BLM9D2527-20AB v.1 | 20170629     | Product data sheet | -             | -          |

## 13. Legal information

### 13.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.ampleon.com>.

### 13.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Ampleon does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

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